

GaN Projects Passdown (Shane), March 03, 2012	To WHOM
1) MOCVD tool procurement	
a. MOCVD facilities tender and preparation	WWZ
b. Ordering/storing of MO sources	WWZ
c. (111) silicon wafer procurement	WWZ
d. Interface with Veeco	WWZ
2) GaN HEMT device fabrication planning and flow	LKB, SHF
a. Runsheet generation	LKB, SHF
b. Planning and tracking of fabrication modules	LKB, SHF
c. Lot running	LKB, SHF
d. Recipe documentation	YL, SHF, LKB
3) Rolls Royce Project	
a. Project leadership and planning	PL
b. GaN power device report	PL
c. Power device simulations	YL and Ravinder Singh
4) Huawei Characterization Project	ST (Try to wrap this)
a. Characterization and Modeling of Balun	SHF
b. Load Pull of high power device	YL
c. Characterization of 1.2V device at high DC voltage	LKB
5) GaN-on-Si Demo wafers	
a. Inventory details	ST to WWZ
b. Import permit and declaration	ST to WWZ
6) GaN PDK	Yuan Li
a. Project PI	Yuan Li if interested
b. Power device analyzer tender/procurement	Yuan Li/Lawrence Selvaraj
c. Pulsed IV equipment tender/procurement	Haifeng Sun
d. Planning of PDK development with software vendors	YL
e. Interface with NTU team for CMOS compatible process	YL / Lawrence
f. Management of load pull system	YL / Haifeng Sun

What Needed to Pass Down	Status
1) Tender Documents and Explanation 2) Determination of contractor for facilities Hook-Up 3) Oversight of hook-up preparation and process	
1) Weizhu has already taken over much of this responsibility	
1) Vendor contact for wafer procurement 2) Explanation of the wafers used for MOCVD growth	
1) Transition communication responsibility to Weizhu	
1) Process flow 2) Runsheets currently generated 3) Understanding of tools involved 4) Understanding of module engineers	
1) Gantt chart schedule	
1) Team up with NanoEP staff to start running lots	
1) Team members need to continue work with FAB staff to look at recipes on specific tools	
1) Project Scope and Deliverables	
1) Power device report outline 2) Responsibilities of Team Members for parts of the report 3) Current draft of report parts	
1) Make sure YL and Ravinder have clear plan for simulations	
1) Work with Hou Debin to figure out dembedding procedure	
1) Work with Li Yihu to learn procedure for taking load pull measurement	
1) Work with Calvin Chua to learn how to do this characterization with temperature adjustable stage	
1) Inventory Documentation 2) Explanation of growth structures	
1) Import permit documents 2) Explanation of procedure for further import of new wafers/ substrate carriers	
1) Documentation 2) Budget 3) Deliverables 4) Original Schedule 5) Supervision of Li Yihu	
1) Tender Documents 2) Determination of vendor after tender response	
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1) Contacts from Agilent, Silvaco	
1) Set up meeting with NTU team	
1) Set up meeting with Yihu to discuss the machine procedures	